

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	10/525207	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/22 06:26
S2	1	"11627026"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/26 11:32
S3	10	("20020167917" "5019531" "5520858" "6424800" "6482266").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/26 13:43
S4	1	"10525207"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/26 12:30
S5	23056	tokyo adj electron.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/26 12:31
S6	9	S5 and fluorinated adj resin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/26 12:31
S7	4	("4277671" "4493983" "5308957" "6137091").PN. OR ("6573482").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/07/26 12:33
S8	74	("4654106" "4857142" "5169408" "5248380").PN. OR ("5314574").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/07/26 12:38
S9	1	S5 and partial adj pressure adj detect\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/26 12:55
S10	28	("4492110" "4773276" "4776207" "4779449" "4793283" "5199994").PN. OR ("5365772").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/07/26 13:00
S11	0	S5 and metallic adj precursor	US-PGPUB; USPAT; USOCR	OR	OFF	2007/07/26 13:00

S12	1	11/086396	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/07/26 13:43
S13	10	("20020167917" "5019531" "5520858" "6424800" "6482266").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/06 09:20
S14	75	("4654106" "4857142" "5169408" "5248380").PN. OR ("5314574").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/08/06 09:48
S15	44	("4544446" "4681776" "4980204" "5032217").PN. OR ("5248380").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/08/06 10:08
S16	1	"4704988".pn.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/08/06 10:08
S17	9	("3459668").PN. OR ("4704988").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/08/06 10:13
S18	0	"09378274"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/06 10:28
S19	1	"09/378274"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/08/06 10:28
S20	7	("4140735" "4947790" "5603169" "5711816").PN. OR ("6444038").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/08/06 10:31
S21	7	("4140735" "4947790" "5603169" "5711816").PN. OR ("6444038").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/08/06 10:36
S22	4	"5009959".pn. "5599654".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/20 13:08
S23	10	("20020167917" "5019531" "5520858" "6424800" "6482266").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/20 13:08
S24	0	S23 and resin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/20 13:08
S25	77	("4654106" "4857142" "5169408" "5248380").PN. OR ("5314574").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/10/20 13:09

S26	0	S25 and S25 and resin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/20 13:09
S27	23593	tokyo adj electron.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/20 13:09
S28	1037	S27 and resin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/20 13:09
S29	5	S27 and resin same (shower adj head gas adj inject\$3 adj plate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/20 13:11
S30	149	resin same (shower adj head gas adj inject\$3 adj plate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/20 13:28
S31	92	S30 and (@ad<="20020823" @rlad<="20020823")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/20 13:30
S32	1547	resin same ((shower adj head gas adj inject\$3 adj plate) (diffus\$3 dispers\$3 divert\$3) adj plate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/20 13:29
S33	1058	resin with ((shower adj head gas adj inject\$3 adj plate) (diffus\$3 dispers\$3 divert\$3) adj plate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/20 13:29
S34	711	resin near7 ((shower adj head gas adj inject\$3 adj plate) (diffus\$3 dispers\$3 divert\$3) adj plate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/20 13:29
S35	56	S34 and (@ad<="20020823" @rlad<="20020823") and (semiconductor wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 11:33
S36	13	("20010027843" "20020167917" "5019531" "5520858" "6424800" "6482266").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 07:51

S37	3	("5460654" "5575854" "5648114").PN. OR ("6482266").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/10/21 07:52
S38	18	("4659401" "4717596" "4791005" "4874634" "4921722" "4980204" "5160542" "5322710" "5324386").PN. OR ("5460654").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/10/21 08:00
S39	23610	tokyo adj electron.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 08:01
S40	11	S39 and ((diffus\$4 dispers\$4 divert\$3) adj plate same support)	US-PGPUB; USPAT; USOCR	OR	OFF	2007/10/21 08:01
S41	5	S40 and (@ad<="20020823" @rlad<="20020823") and (semiconductor wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 08:07
S42	0	S39 and (bubbler same plate same support)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 08:06
S43	1144	S39 and ((partition plate) same support)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 08:28
S44	709	S43 and (@ad<="20020823" @rlad<="20020823") and (semiconductor wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 08:29
S45	137	S39 and kasai.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 08:21
S46	0	bubbler same gas adj inject\$3 adj plate same support	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 08:22
S47	7	bubbler same (gas adj inject\$3 support) adj plate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 08:22
S48	12	("3174291" "3480015").PN. OR ("4487619").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/10/21 08:26

S49	2	support adj plate same hollow and bubbler	US-PGPUB; USPAT; USOCR	OR	OFF	2007/10/21 08:27
S50	2	support adj plate same hollow and bubbler	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 08:27
S51	35	S39 and ((partition plate) same support) same hollow	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 08:28
S52	29	S51 and (@ad<="20020823" @rlad<="20020823")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 09:28
S53	0	hollow adj support adj plate and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 09:28
S54	39	hollow adj support adj plate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 09:28
S55	26	S54 and (@ad<="20020823" @rlad<="20020823")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 10:10
S56	6	hollow adj support\$3 adj plate same member	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 09:29
S57	2	"6772072".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 10:10
S58	264	showerhead same coat\$3 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 10:10
S59	182	S58 and (@ad<="20020823" @rlad<="20020823")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 10:11

S60	2	"5614026".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 11:30
S61	2	"5580822".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 11:31
S62	2	"5985140".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 11:31
S63	2	"5958140".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 11:32
S64	804	showerhead with heat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 11:32
S65	622	showerhead with heat\$3 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 11:34
S66	420	S65 and (@ad<="20020823" @rlad<="20020823") and (semiconductor wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 12:19
S67	430	heat\$3 near7 showerhead and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 11:34
S68	304	S67 and (@ad<="20020823" @rlad<="20020823") and (semiconductor wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 12:11
S69	2	"20040129224"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 11:50
S70	2	"20020092615"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 12:18

S71	2	"20020006577"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 12:14
S72	700	process\$3 adj chamber and support\$3 adj member same plate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 12:19
S73	403	S72 and (@ad<="20020823" @rlad<="20020823") and (semiconductor wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 12:46
S74	0	S72 and (@ad<="20020823" @rlad<="20020823") same (hollow open\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 12:20
S75	2	"11057111"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 12:46
S76	1	"11/057111"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 12:46
S77	2	"20050133161"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/21 13:17
S78	23	("20010027843" "20020167917" "5019531" "5520858" "5614026" "5891253" "5989345" "6424800" "6482266" "6499425" "6772072").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/22 06:26
S79	7	("4770630" "5421895" "5580822" "5651827" "6058926").PN. OR ("6424800"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/10/22 06:41

S80	34	("20020078894" "20030111014" "20030121608" "20030232138" "20040013577" "20040016404" "20040025370" "20040083963" "20040083965" "4723967" "4916828" "4947790" "5019423" "5227340" "5276585" "5377429" "5381605" "5562132" "5674574" "5707424" "5953634" "5989305" "6058012" "6077356" "6089184" "6202591" "6244331" "6424800" "6444038" "6470144" "6520218" "6581649" "6840252" "6909839").PN. OR ("7261118").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/10/22 06:43
S81	4	("4916828" "5019423").PN. OR ("5989305").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/10/22 07:01
S82	10	("2701901" "2738762").PN. OR ("5019423").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/10/22 07:21
S83	1	"6424800".pn.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/10/22 07:24
S84	7	2004/0025370	US-PGPUB; USPAT; USOCR	OR	OFF	2007/10/22 07:28
S85	1	"20040025370"	US-PGPUB; USPAT; USOCR	OR	OFF	2007/10/22 07:28
S86	2	"20030042630"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 09:09
S87	963	bubbler same (metal metallic solid) same heat\$3 same gas	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 09:16
S88	256	S87 and (@ad<="20020823" @rlad<="20020823") and (semiconductor wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 09:16
S89	2	"5902651".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 10:04

S90	1167	bubbler same temperature same heat\$3 same control\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 10:11
S91	290	S90 and (@ad<="20020823" @rlad<="20020823") and (semiconductor wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 10:11
S92	340	bubbler same temperature same heat\$3 same controller	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 10:13
S93	126	S92 and (@ad<="20020823" @rlad<="20020823") and (semiconductor wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 10:13
S94	4	"4436674".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 10:50
S95	108	S93 and pressure same temperature	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 11:01
S96	2	S93 and McMenamin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 11:02
S97	2	"20040247787"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 12:52
S98	2	"5902651".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 13:06
S99	2	"6442736".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 13:12
S100	2	"4767429".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 14:06

S101	25812	tokyo adj electron.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 14:07
S102	37	S101 and bubbler same carrier adj gas	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 14:07
S103	2	"7037560".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/08/15 14:09

8/ 15/ 2008 3:23:07 PM

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